



**PARA LIGHT ELECTRONICS CO., LTD.**

11F, No.8, Jiankang Rd,Zhonghe Dist,New Taipei City 253, Taiwan

Tel: 886-2-2225-3733 Fax: 886-2-2225-4800

E-mail: [para@para.com.tw](mailto:para@para.com.tw) http:// [www.paralighttaiwan.com](http://www.paralighttaiwan.com)

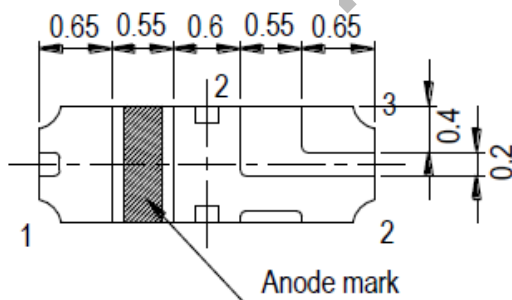
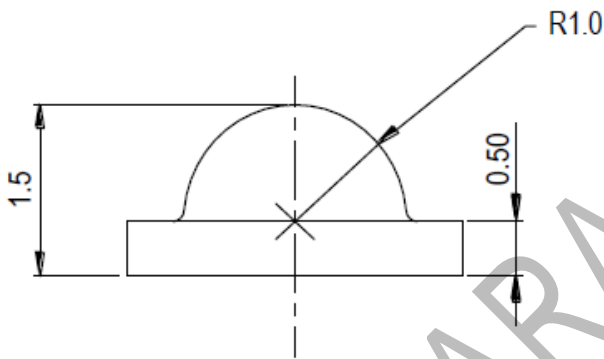
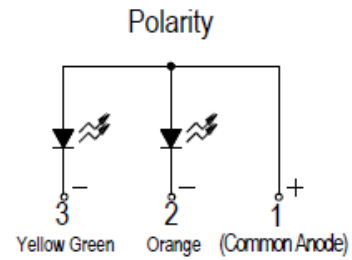
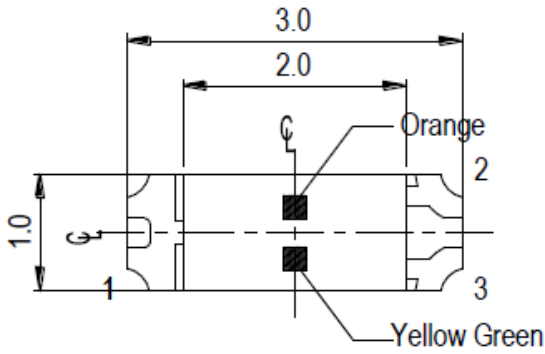
DATA SHEET

PART NO. : L-S115JGJFCT-HD

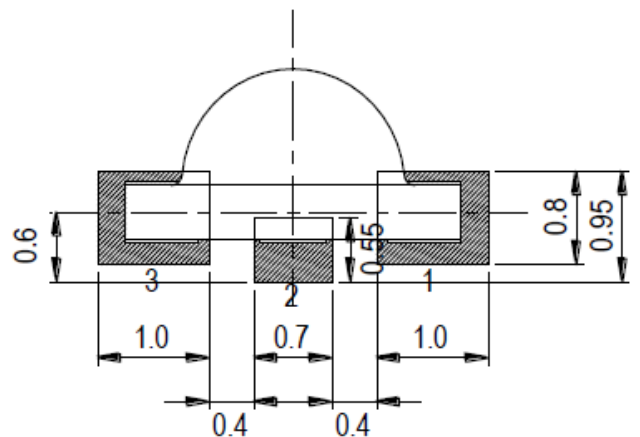
REV : A / 0

CUSTOMER'S APPROVAL : \_\_\_\_\_ DCC : \_\_\_\_\_

PACKAGE DIMENSIONS



Recommended Solder Pad



Note:  
Tolerance unless mentioned is  $\pm 0.1$  mm, Unit = mm.



3.0\*1.0\*1.5 mm SMD LED

L-S115JGJFCT-HD

REV:A / 0

## FEATURES

- \* 3.0\*1.0\*1.5 mm SMD LED
- \* Side view LED
- \* Compatible with infrared and vapor phase reflow solder process
- \* Wide viewing angle

## CHIP MATERIALS

- \* Dice Material : AlGaInP
- \* Light Color : Brilliant Yellow Green & Orange
- \* Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING : ( Ta = 25°C )

SYMBOL	PARAMETER	RATING		UNIT
		JG	JF	
PD	Power Dissipation	60	60	mW
If	Forward Current	25	25	mA
Ifp	Peak Forward Current (1/10 duty cycle 0.1ms)	60	60	mA
VR	Reverse Voltage	5		V
ESD	Electrostatic Discharge Threshold(HBM)	2000	2000	V
Topr	Operating Temperature Range	-40 ~ + 85		°C
Tstg	Storage Temperature Range	-40 ~ + 100		°C
Tsld	Soldering Temperature	Reflow Soldering : 260 °C for 10 sec Hand Soldering : 350 °C for 3 sec		

## ELECTRO-OPTICAL CHARACTERISTICS : ( Ta = 25°C )

SYMBOL	PARAMETER	TEST CONDITION	VALUE			UNIT	
			MIN.	TYP.	MAX.		
VF	Forward Voltage	IF = 20mA	JG	1.7	2.4	V	
			JF	1.7	2.4		
IR	Reverse Current	VR = 5V			10	μA	
λp	Peak Emission Wavelength	IF = 20mA	JG	575		nm	
			JF	611			
λD	Dominant Wavelength	IF = 20mA	JG	567.5	571.5	575.5	nm
			JF	600	605	610	
2θ1/2	Half Intensity Angle	IF = 20mA		120		deg	
Iv	Luminous Intensity	IF = 20mA	JG	45	90	mcd	
			JF	90	225		

Typical Electro-Optical Characteristics Curves  
(25°C Ambient Temperature Unless Otherwise Noted)

JG/JF:

Fig.1-Forward Voltage Shift vs. Junction Temperature

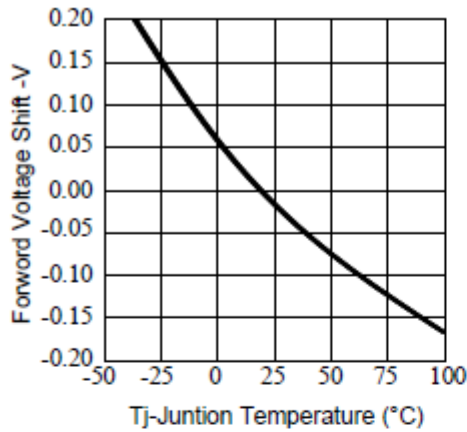


Fig.2-Relative Luminous Intensity vs. Forward Current

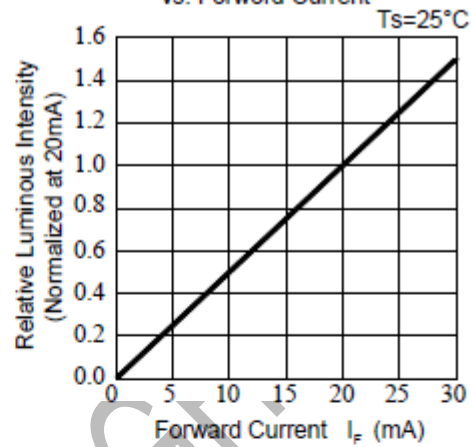


Fig.3-Relative Luminous Intensity vs. Junction Temperature

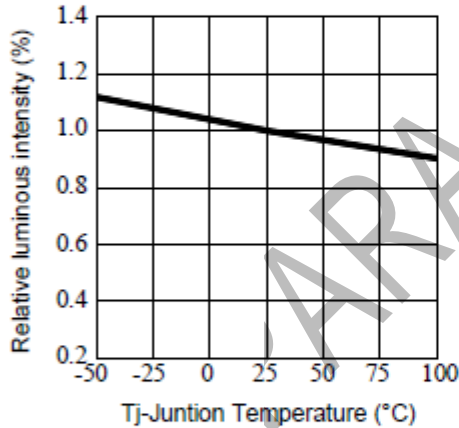


Fig.4-Forward Current vs. Forward Voltage

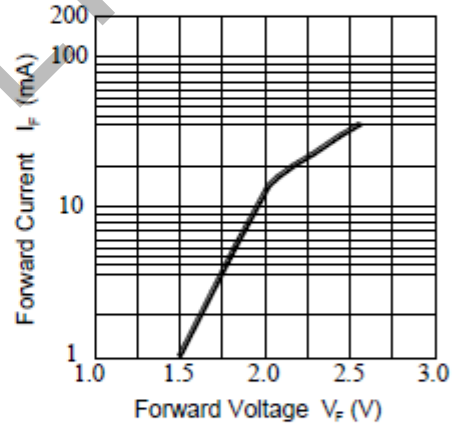


Fig.5-Max. Driving Forward Current vs. Soldering Temperature

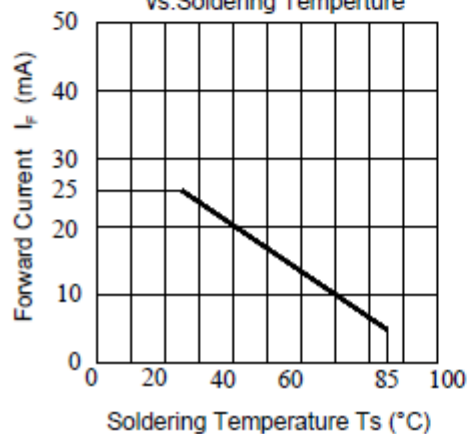
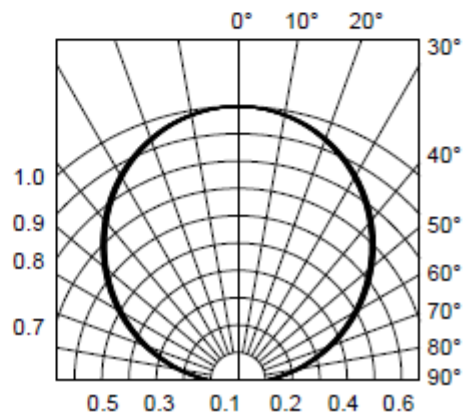


Fig.6-Radiation Diagram





3.0\*1.0\*1.5 mm SMD LED

L-S115JGJFCT-HD

REV:A / 0

**Bin Range of Luminous Intensity(JG)**

Bin Code	Min.	Max.	Unit	Condition
AP1	45	57	mcd	I <sub>F</sub> =20mA
AP2	57	72		
AQ1	72	90		

**Bin Range of Luminous Intensity(JF)**

Bin Code	Min.	Max.	Unit	Condition
QA	90	140	mcd	I <sub>F</sub> =20mA
PA	140	225		

Note: Tolerance of Luminous Intensity:  $\pm 10\%$

**Bin Range of Dominant Wavelength(JG)**

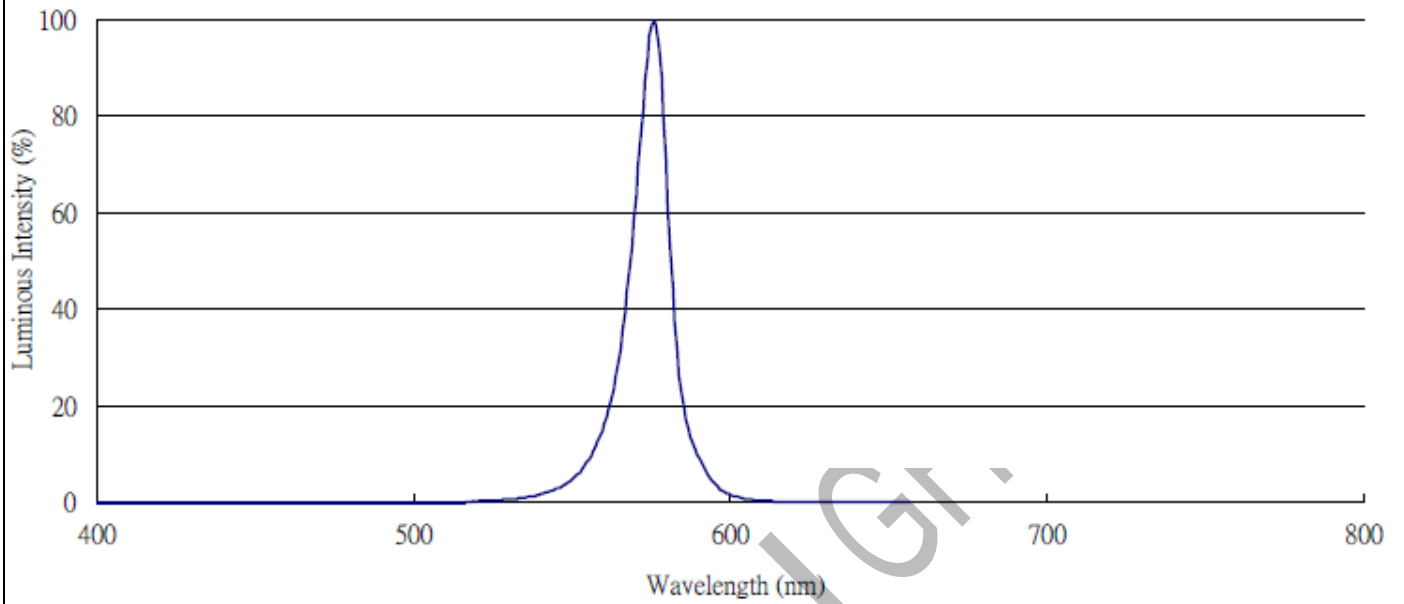
Bin Code	Min.	Max.	Unit	Condition
AG15	567.5	569.5	nm	I <sub>F</sub> =20mA
AG16	569.5	571.5		
AG17	571.5	573.5		
AG18	573.5	575.5		

**Bin Range of Dominant Wavelength(JF)**

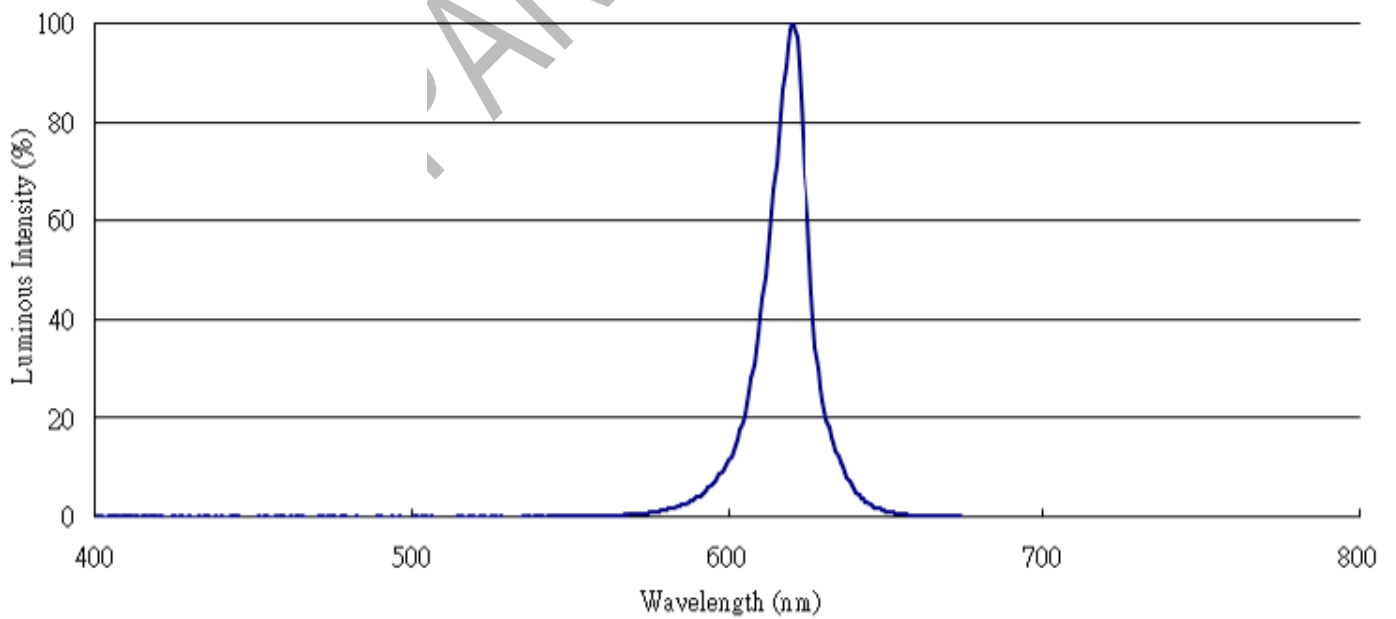
Bin Code	Min	Max	Unit	condition
OA	600	605	nm	IF=20mA
OB	605	610		

Note: Tolerance of Dominant Wavelength:  $\pm 1\text{nm}$

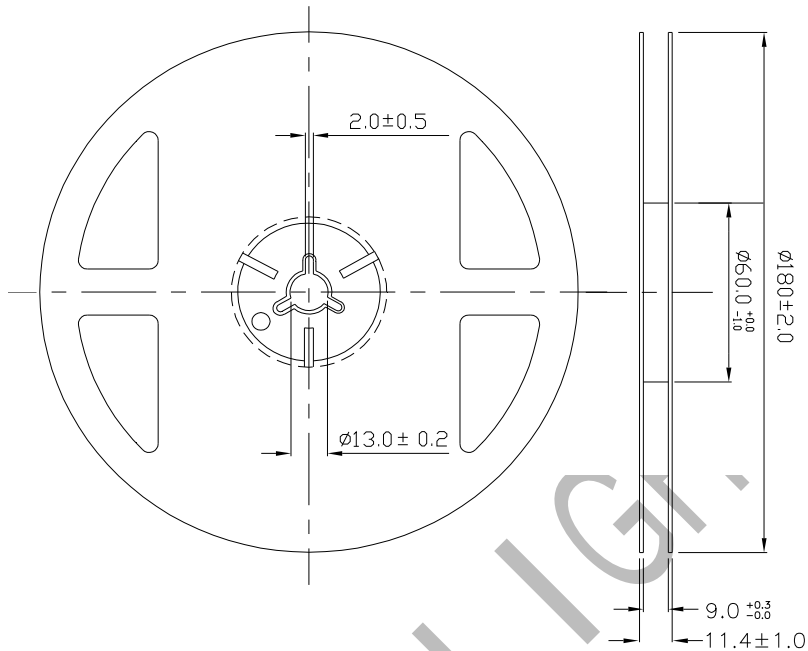
**Spectrum Distribution(JG)**



**Spectrum Distribution(JF)**



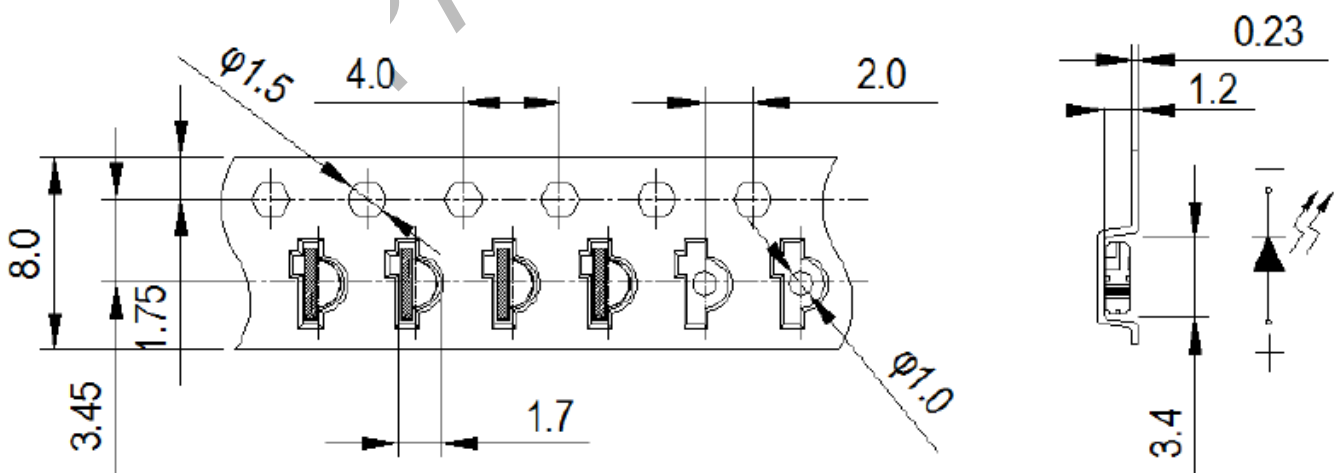
**Reel Dimensions**



Note: Tolerances unless mentioned  $\pm 0.1$ mm, Unit = mm.

Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel

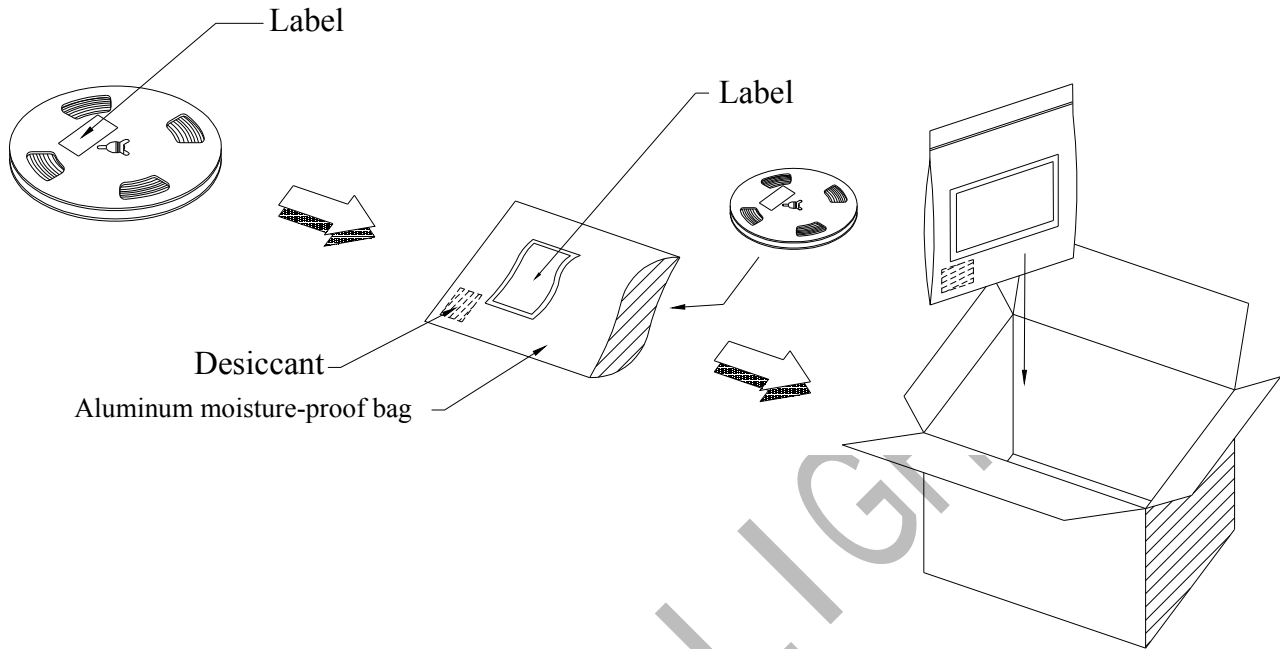
Progressive direction



Note:

1. Tolerance unless mentioned is  $\pm 0.1$ mm, Unit = mm.
2. Minimum packing amount is 1000pcs per reel.

**Moisture Resistant Packing Process**



**Reliability Test Items and Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 5min ∩ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 15min ∩ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
6	High Temperature Storage	Ta=100°C	1000 Hrs.	22 PCS.	0/1
7	DC Operation Life	Ta=25°C, I <sub>F</sub> = 20 mA	1000 Hrs.	22 PCS.	0/1



**Precautions for Use**

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

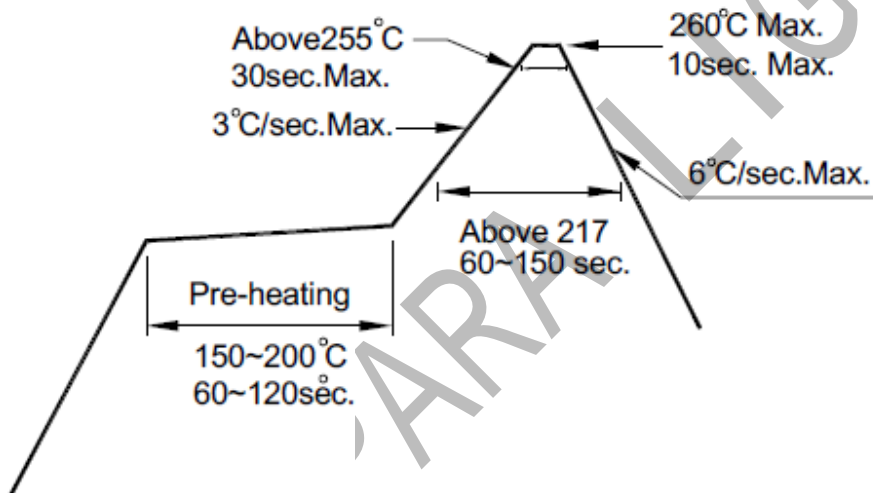
2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.